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- Output Ports Have Equivalent 22-Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low-Static Power Dissipation
- Members of the Texas Instruments *Widebus™* Family
- Support Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})
- Support Unregulated Battery Operation Down to 2.7 V
- High-Impedance State During Power Up and Power Down
- Typical V_{OLP} (Output Ground Bounce)
 < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Bus-Hold Data Inputs Eliminate the Need for External Pullup/Pulldown Resistors
- Power Off Disables Inputs/Outputs, Permitting Live Insertion
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

The 'LVTH162373 are16-bit transparent D-type latches with 3-state outputs designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.



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SN54LVTH162373 ... WD PACKAGE SN74LVTH162373 ... DGG OR DL PACKAGE (TOP VIEW)

1OE	i ₁	48	1 1LE
1Q1 [2	47	1D1
1Q2		46	1D2
GND [4	45	GND
1Q3 [5	44	1D3
1Q4 [6	43	1D4
V _{CC} [7	42	Vcc
1Q5 [8	41	1D5
1Q6 [40] 1D6
GND [10	39] GND
1Q7 [11	38] 1D7
1Q8 [12	37] 1D8
2Q1 [13	36	2D1
2Q2 [14	35] 2D2
GND [15	34] GND
2Q3 [16	33	2D3
2Q4 [17	32] 2D4
V _{CC} [18	31	V _{CC}
2Q5 [19	30	2D5
2Q6 [20	29	2D6
GND [21	28] GND
2Q7 [22	27	2D7
2Q8 [23	26	2D8
2 <mark>0E</mark> [24	25	2LE

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description (continued)

The 'LVTH162373 can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without interface or pullup components.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

The outputs, which are designed to source or sink up to 12 mA, include $22 \cdot \Omega$ series resistors to reduce overshoot and undershoot.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVTH162373 is available in TI's shrink small-outline (DL) and thin shrink small-outline (DGG) packages, which provide twice the I/O pin count and functionality of standard small-outline packages in the same printed circuit board area.

The SN54LVTH162373 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74LVTH162373 is characterized for operation from -40° C to 85° C.

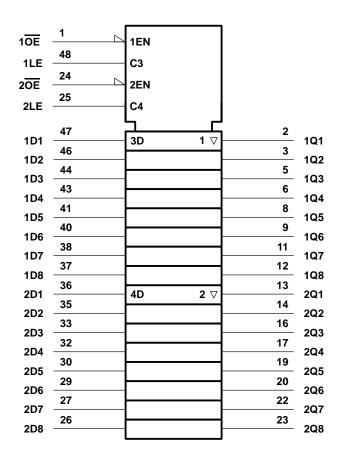
(each o-bit section)									
	INPUTS	OUTPUT							
OE	LE	D	Q						
L	Н	Н	Н						
L	н	L	L						
L	L	Х	Q ₀						
н	Х	Х	z						

FUNCTION TABLE (each 8-bit section)



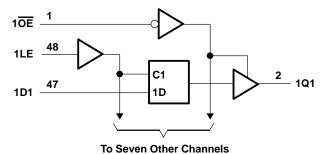
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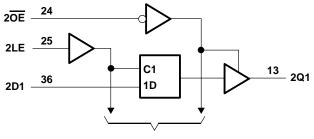
logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





To Seven Other Channels



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} $-0.5 V$ to $4.6 V$ Input voltage range, V_I (see Note 1) $-0.5 V$ to $7 V$ Voltage range applied to any output in the high or power-off state, V_O (see Note 1) $-0.5 V$ to $7 V$ Current into any output in the low state, I_O 30 mA Current into any output in the high state, I_O (see Note 2) 30 mA Input clamp current, I_{IK} ($V_I < 0$) -50 mA Output clamp current, I_{OK} ($V_O < 0$) -50 mA Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 3): DGG package $0.85 W$ DL package $1.2 W$
Storage temperature range, T _{stg}

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. This current flows only when the output is in the high state and $V_O > V_{CC}$.

3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the *ABT Advanced BiCMOS Technology Data Book*.

recommended operating conditions (see Note 4)

			SN54LVTH	162373	SN74LVTH	UNIT	
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage	2.7	3.6	2.7	3.6	V	
VIH	High-level input voltage		2	M	2		V
VIL	Low-level input voltage		0.8		0.8	V	
VI	Input voltage	4	5.5		5.5	V	
ЮН	High-level output current		5	12		-12	mA
IOL	Low-level output current		201	12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled	90'	10		10	ns/V
Δt/ΔVCC	Power-up ramp rate	Q 200		200		μs/V	
Т _А	Operating free-air temperature	-55	125	-40	85	°C	

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54	LVTH16	2373	SN74			
		TEST CONDITIONS			TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK		V _{CC} = 2.7 V,	lj = –18 mA			-1.2			-1.2	V
Vон		V _{CC} = 3 V,	I _{OH} = -12 mA	2			2			V
VOL		V _{CC} = 3 V,	I _{OL} = 12 mA			0.8			0.8	V
		V _{CC} = 0 or 3.6 V,	V _I = 5.5 V			10			10	
	Control inputs	V _{CC} = 3.6 V,	$V_I = V_{CC}$ or GND			±1			±1	
I	_		$V_I = V_{CC}$			1			μA	
	Data inputs	V _{CC} = 3.6 V	$V_{I} = 0$			-5			-5	
loff	•	V _{CC} = 0,	V_{I} or $V_{O} = 0$ to 4.5 V		4	÷±100			±100	μA
	A inputs	V _{CC} = 3 V	VI = 0.8 V	75	75			75		
			V _I = 2 V	-75	2		-75			μΑ
IOZH		V _{CC} = 3.6 V,	V _O = 3 V		<u>í</u>	5			5	μA
IOZL		V _{CC} = 3.6 V,	V _O = 0.5 V	4	3	-5			-5	μA
IOZPU [‡]	:	$V_{CC} = 0$ to 1.5 V, $V_{O} =$	0.5 V to 3 V, $\overline{OE} = 0$	5	,	±100			±100	μA
IOZPD [‡]		V _{CC} = 1.5 V to 0, V _O =	0.5 V to 3 V, OE = 0			±100			±100	μA
			Outputs high			0.19			0.19	
ICC		$V_{CC} = 3.6 V, I_{O} = 0,$	Outputs low			5		5		mA
		$V_{I} = V_{CC} \text{ or } GND$	Outputs disabled			0.19			0.19	
∆ICC§			$C = 3 V$ to 3.6 V, One input at $V_{CC} - 0.6 V$, her inputs at V_{CC} or GND 0.2		0.2	mA				
Ci		V _I = 3 V or 0		1	3			3		pF
Co		V _O = 3 V or 0			9			9		pF

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. [‡] This parameter is characterized but not production tested.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		s	N54LVT	H162373	;	SN74LVTH162373				
		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		UNIT
		MIN	MAX	🔨 MIN	MAX	MIN	MAX	MIN	MAX	
tw	Pulse duration, LE high	3	00	3		3		3		ns
t _{su}	Setup time, data before LE \downarrow	1	R	0.6		1		0.6		ns
th	Hold time, data after LE \downarrow	1	.6.	1.1		1		1.1		ns



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switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

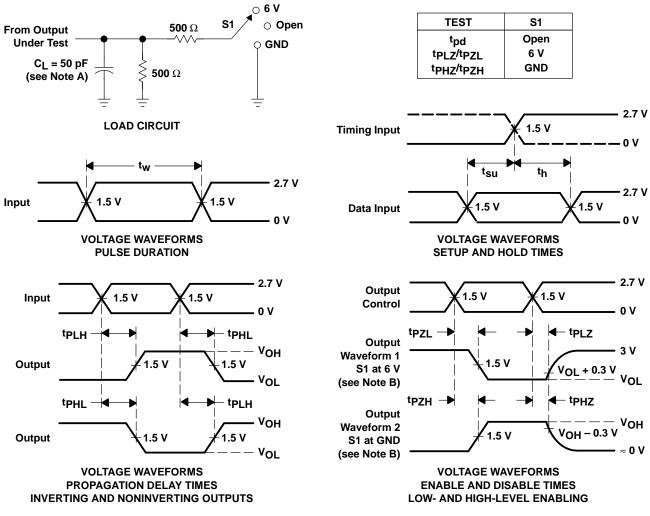
			S	N54LVT	H162373	3		SN74	LVTH16	2373			
PARAMETER	FROM TO (INPUT) (OUTPUT)		V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT	
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN	MAX		
^t PLH	D	D	Q	1.8	4.8		5.3	1.9	3.1	4.6		5.1	ns
^t PHL		Q	1.8	4.2	EW	4.5	1.9	2.8	4		4.3	115	
^t PLH	LE	LE	Q	2.1	5.3	EL	6	2.2	3.4	5.1		5.8	ns
^t PHL			3	2.1	4.9	4a	4.5	2.2	3.2	4.6		4.3	115
^t PZH	OE	Q	1.7	5.6		6.8	1.8	3.2	5.4		6.6	ns	
tPZL	OE	ý	1.7	5,1		5.7	1.8	3.2	4.9		5.5	115	
^t PHZ	OE	Q	2.3	5.6		5.9	2.4	3.8	5.4		5.7	ns	
^t PLZ	0E	y y	2.1	5.6		5.6	2.2	3.5	5.1		5	115	

[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CI includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
- Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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